


## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	PATTERNED STRAINED SEMICONDUCTOR SUBSTRATE AND DEVICE		
Application Type : regular, utility			
Correspondence address:			
Customer Number:		29,625	
Inventors Information:			
<u>Inventor 1:</u>			
<b>Applicant Authority Type:</b>	Inventor		
<b>Citizenship:</b>	CN		
<b>Given Name:</b>	Kangguo		
<b>Family Name:</b>	Cheng		
<b>Residence:</b>			
<b>City of Residence:</b>	Beacon		
<b>State of Residence:</b>	NY		
<b>Country of Residence:</b>	US		
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<b>Address-2 of Mailing Address:</b>			
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<b>State of Mailing Address:</b>	NY		
<b>Postal Code of Mailing Address:</b>			
<b>Country of Mailing Address:</b>	US		
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<u>Inventor 2:</u>			
<b>Applicant Authority Type:</b>	Inventor		
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<b>Family Name:</b>	Divakaruni		
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<b>City of Residence:</b>	Ossining		

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Publication Information:  
Suggested Figure for Publication - 1  
Suggested Classification -  
Suggested Technology Center -  
Total Number of Drawing Sheets - 39

Assignee 1:

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